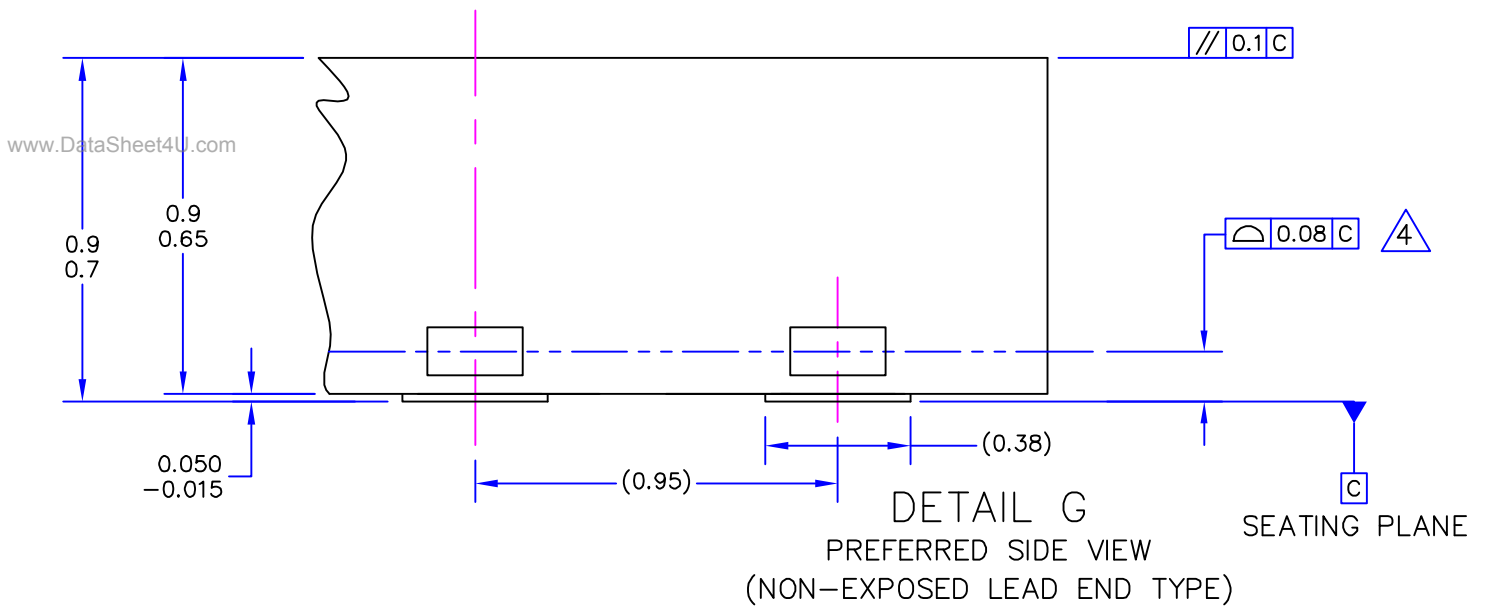
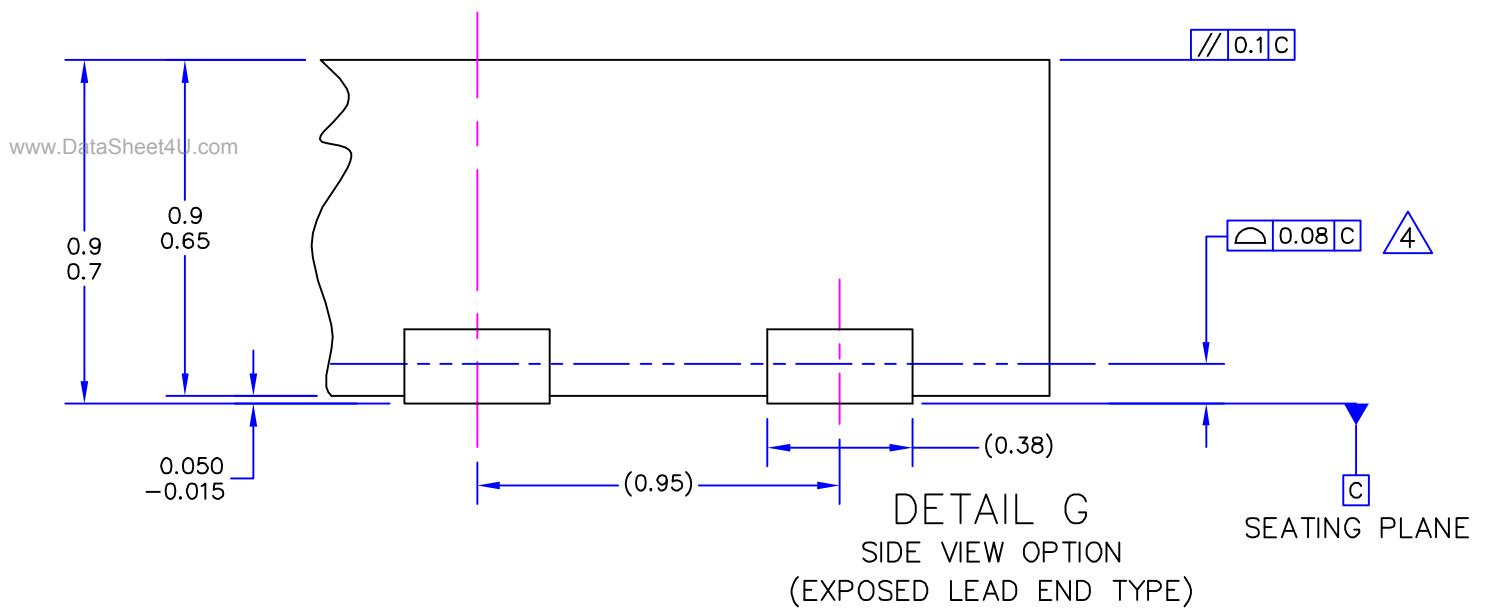
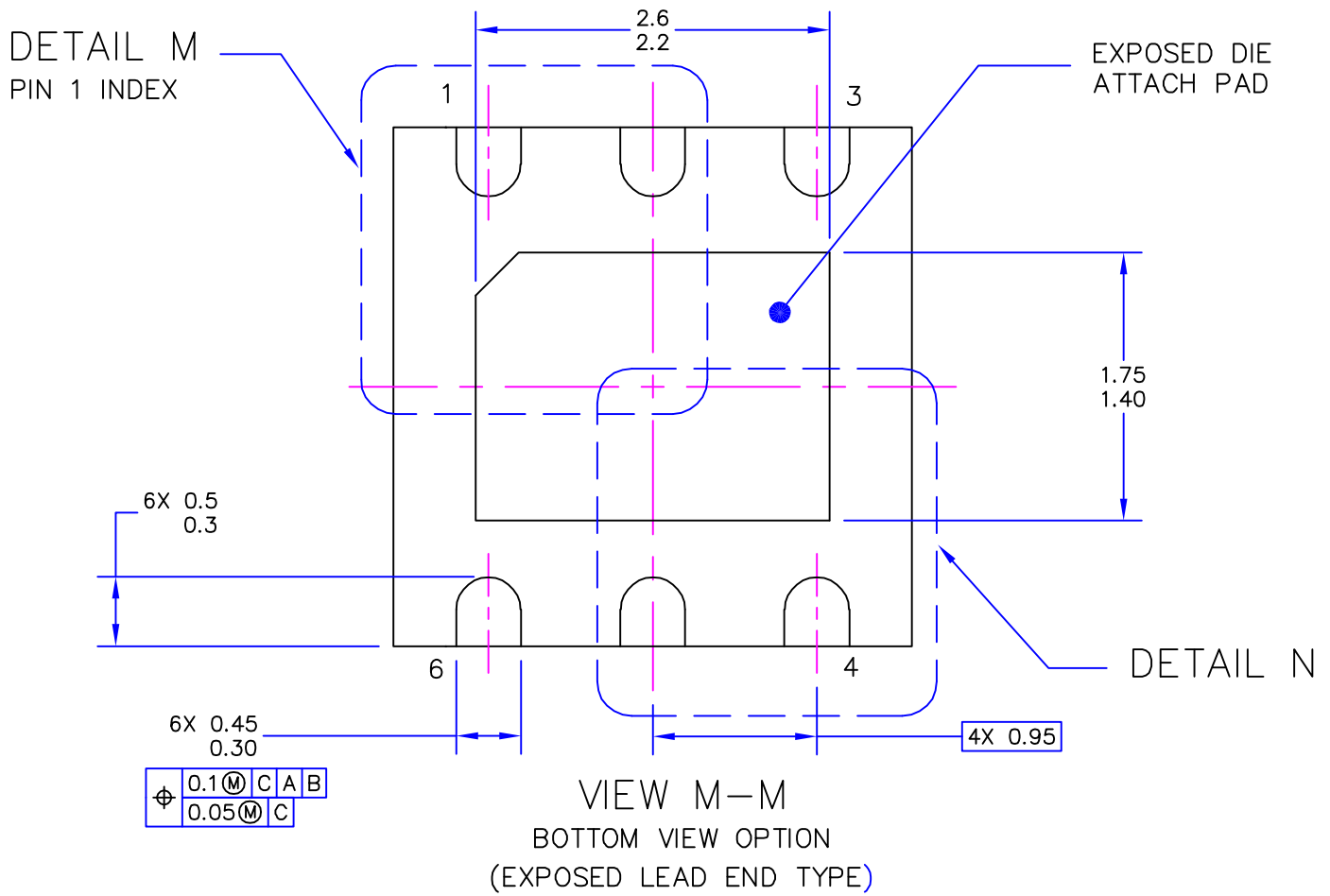


⌀	0.1	M	C	A	B
	0.05	M	C		

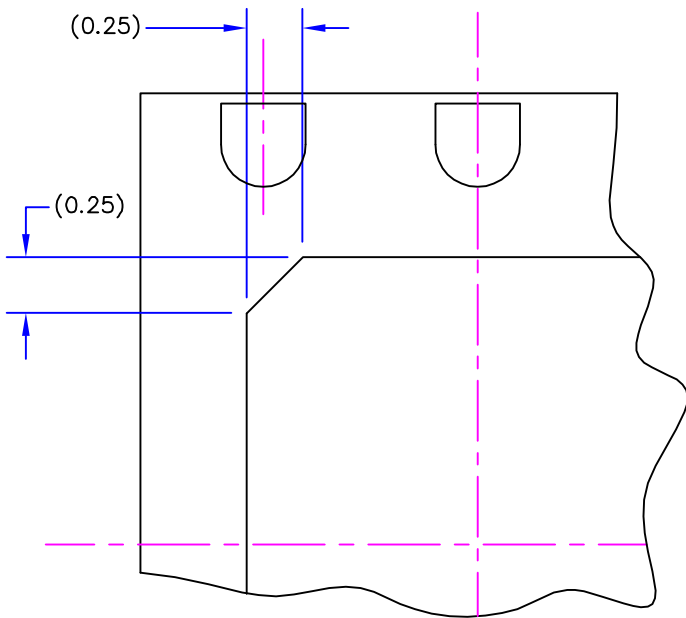
VIEW M-M
PREFERRED BOTTOM VIEW
(NON-EXPOSED LEAD END TYPE)



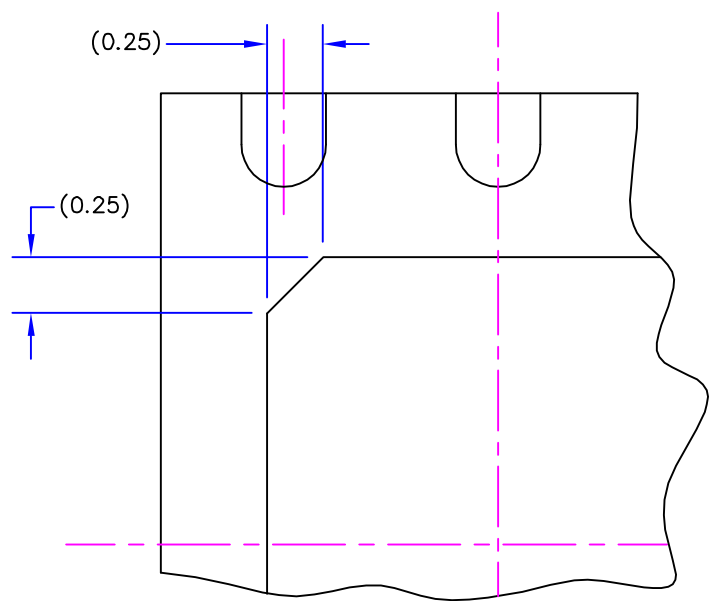
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TITLE: THERMALLY ENHANCED DUAL FLAT NON-LEADED PACKAGE (DFN) 6 TERMINAL, 0.95 PITCH (3 X 3 X 0.8)	DOCUMENT NO: 98ARL10602D	REV: C	
	CASE NUMBER: 1677-02	16 DEC 2008	
	STANDARD: FREESCALE STD		



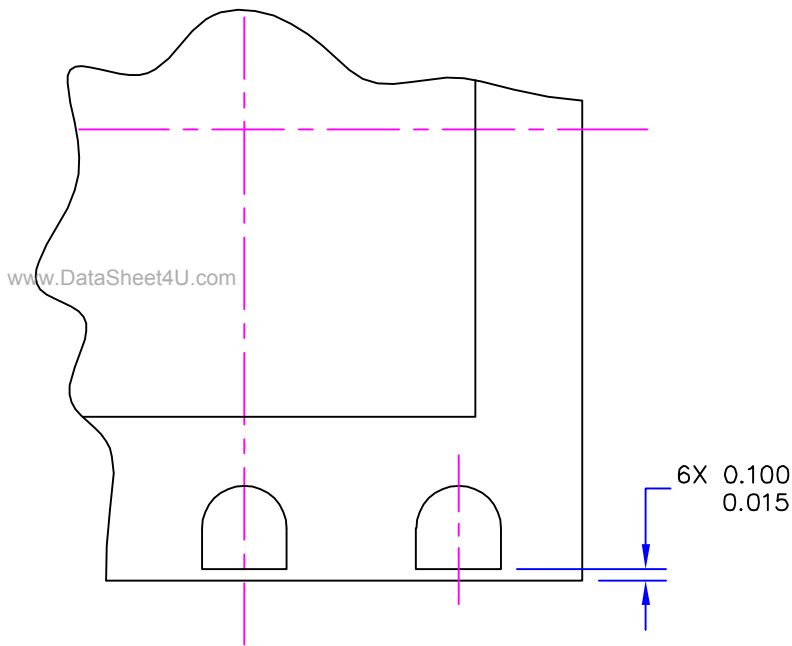
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	CASE NUMBER: 1677-02	16 DEC 2008	
	STANDARD: FREESCALE STD		



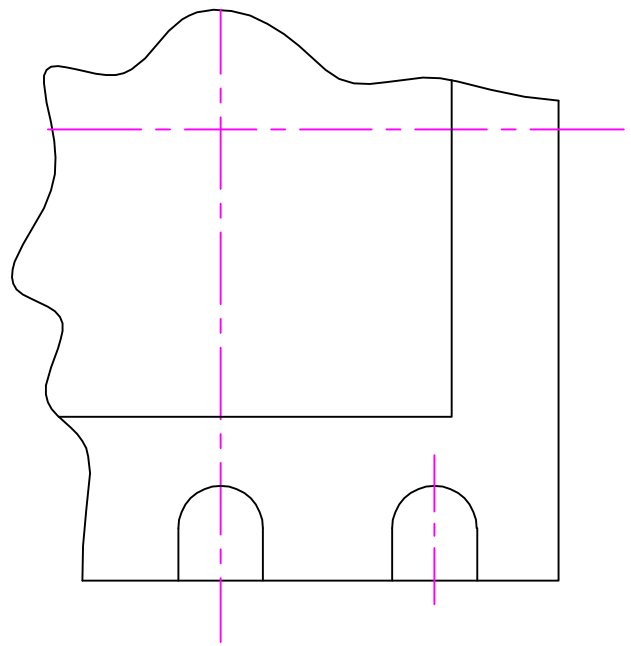
DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL M
BACKSIDE PIN 1 INDEX OPTION




DETAIL N
PREFERRED CORNER CONFIGURATION



DETAIL N
CORNER CONFIGURATION OPTION

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<p>TITLE: THERMALLY ENHANCED DUAL FLAT NON-LEADED PACKAGE (DFN) 6 TERMINAL, 0.95 PITCH (3 X 3 X 0.8)</p>	<p>DOCUMENT NO: 98ARL10602D</p>	<p>REV: C</p>	
	<p>CASE NUMBER: 1677-02</p>	<p>16 DEC 2008</p>	
	<p>STANDARD: FREESCALE STD</p>		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HV-PDSO-N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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